

Inc.

4,194,304 bit CMOS High Speed Static RAM

### **Features**

Fast Access times of 85/100/120 ns.

JEDEC 68 J leaded Ceramic Surface Mount Package.

User Configurable as 8 / 16 / 32 bit wide.

**Operating Power** 

90 / 180 / 300 mW (typ).

Low Power Standby 40 µW (typ) -L version.

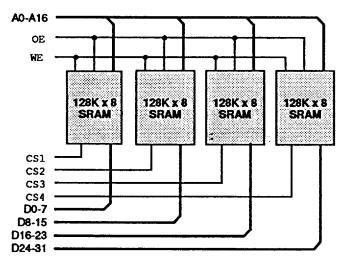
3.0V Battery Back-up Capability

TTL Compatible Inputs and Outputs

**Completely Static Operation** 

May be processed to non-compliant MIL-STD-883

### **Block Diagram**

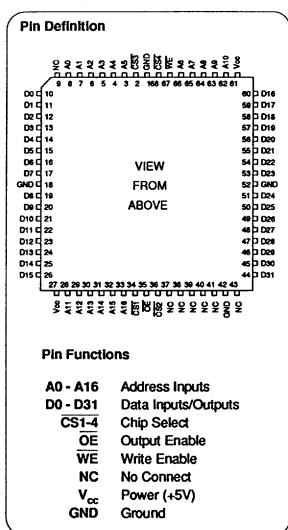


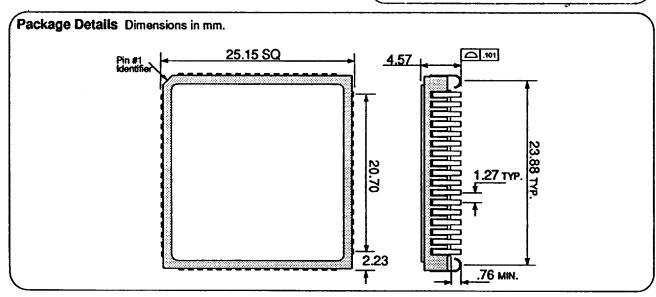
# 128K x 8 SRAM Module

## PUMA 67S4000-85/10/12

Issue 1.0 : January 1993

# ADVANCE PRODUCT INFORMATION





# Absolute Maximum Ratings (1)

ISSUE 1.0 : JANUARY 1993

Voltage on any pin relative to V <sub>x</sub> (2)	$V_{\tau}$	-0.5V to +7	٧
Power Dissipation	$P_{\tau}$	4	W
Storage Temperature	T <sub>stg</sub>	-55 to +125	.c

- Notes: (1) Stresses above those listed may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to the conditions above for extended periods may affect device reliability.
  - (2) Pulse width: 3.0V for less than 30ns.

#### **Recommended Operating Conditions**

		min	typ	max	Units
Supply Voltage	V <sub>cc</sub>	4.5	5.0	5.5	V
Input High Voltage	V <sub>₩</sub>	2.2	•	V <sub>cc</sub> +0.3	V
Input Low Voltage	V."	-0.3 <sup>(1)</sup>	-	8.0	V
Operating Temperature	Ť.	0	-	70	°C
	TÃ	-40	-	85	°C (67S4000I)
· ·	TM	-55	-	125	°C (67S4000M,67S4000MB)

Note: (1) V<sub>n</sub> can be -3.0V pulse of less than 30ns.

# DC Electrical Characteristics (V. =5V+10%.T.=-55°C to +125°C)

Parameter	S	ymbol	Test Condition	min	<i>typ</i> <sup>(1)</sup>	max	Unit
Input Leakage Current		l <sub>IH</sub>	V <sub>N</sub> = 0V to V <sub>cc</sub>	-	-	2	μΑ
Output Leakage Current	32 bit	الم	$\overline{CS}^{(2)} = V_{H}$ or $\overline{OE} = V_{H'}$ $V_{HO} = 0V$ to $V_{CC}$	-	-	8	μΑ
Operating Supply Current	32 bit	1 <sup>cc35</sup>	$\overline{CS}^{(2)} = V_{ij}$ , $I_{ij} = 0 \text{mA}$ , $V_{ij} \ge V_{ijk} \ge V_{ijk}$	4	60	180	mΑ
Average Supply Current	32 bit	l <sub>CC32</sub>	$\overline{CS}^{(2)} = V_{ii}$ , Minimum cycle, $I_{io} = 0$ mA	-	180	320	mA
	16 bit	I <sub>CC16</sub>	As above	-	90	160	mA
	8 bit	l <sub>ccs</sub>	As above	-	45	80	mΑ
Standby Supply Current TI	TL levels	l <sub>sa</sub>	CS(2) = V <sub>H</sub>	-	4	12	mΑ
CMC	S levels	 	$\overline{\text{CS}}^{(2)} \ge V_{\infty}^{-0.2V}, 0.2V \ge V_{\infty}^{-0.2V}$	-	0.08	8	mΑ
	L-Part	I <sub>SB2</sub>	$\overline{CS}^{(2)} \ge V_{CC} - 0.2V, 0.2V \ge V_{M} \ge V_{CC} - 0.2V$	-	8	400	μΑ
Output Voltage Low		ν <sub>α</sub>	l <sub>ot</sub> =2.1mA	-	-	0.4	٧
Output Voltage High		V <sub>OH</sub>	I <sub>OH</sub> =-1.0mA	2.4	-	-	V

Notes: (1) Typical values are at V<sub>cc</sub>=5.0V,T<sub>A</sub>=25°C and specified loading.

(2) CS above is accessed through CS1-4 These inputs must be operated simultaneously for 32 bit mode, in pairs for 16 bit mode and singly for 8 bit mode.

## Capacitance (V\_=5V±10%,T,=25°C)

Parameter		Symbol	Test Condition	typ	max	Unit
Input Capacitance	Address, OE, WE	C <sub>IN1</sub>	V <sub>N</sub> =0V	-	32	pF
• •	CS1-4	C <sub>m</sub>	V_n=0V	-	8	рF
I/O Capacitance:	D0-D31	C'KO	V <sub>vo</sub> =0∨	-	32	рF

Note: This parameter is calculated and not measured.

#### **AC Test Conditions**

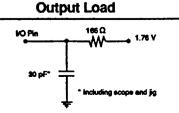
*PUMA m	nodule tested	in 32bit	mode.
---------	---------------	----------	-------

\*Input pulse levels: 0.0V to 3.0V

\*Input rise and fall times: 5 ns

\*Input and Output timing reference levels: 1.5V

\*V\_=5V±10%



## Operating Modes

PUMA 67S4000-85/10/12

The Table below shows the logic inputs required to control the operating modes of each of the SRAMs on the PUMA 67S4000

Mode	CS	ŌĒ	WE	V <sub>∞</sub> Current	I/O Pin	Reference Cycle
Not Selected	1	Х	Х	I <sub>SB</sub> , I <sub>SB1</sub>	High Z	-
Read	0	0	1	I <sub>cc</sub>	D <sub>out</sub>	Read Cycle
Write	0	1	0	I <sub>cc</sub>	D <sub>IN</sub>	Write Cycle No.1
Write	0	0	0	I <sub>cc</sub>	D <sub>IN</sub>	Write Cycle No.2

 $0 = V_{t}$  $X = V_{IL}$  or  $V_{IH}$ 

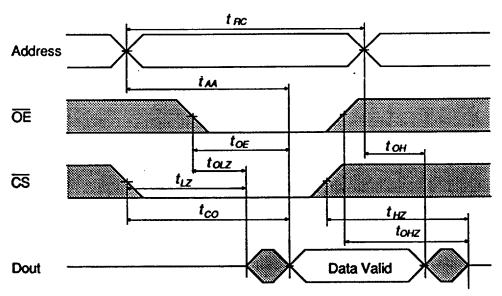
Note:  $\overline{\text{CS}}$  is accessed through  $\overline{\text{CS1-4}}$ . For correct operation,  $\overline{\text{CS1-4}}$  must operate simultaneously for 32 bit operation, in pairs for 16 bit operation, or singly for 8 bit operation.

# **Electrical Characteristics & Recommended AC Operating Conditions**

	Cycle
козп	I VCIA
, cuu	UIUIU

		85		10		12			
Parameter	Symbol	min	max	min	max	min	max	Units	Notes
Read Cycle Time	t <sub>RC</sub>	85	-	100	-	120	-	ns	
Address Access Time	t <sub>M</sub>	-	85	-	100	-	120	ns	
Chip Select Access Time	t <sub>∞</sub>	-	85	-	100	-	120	ns	
Output Enable to Output Valid	t <sub>o∈</sub>	-	40	-	50	-	60	ns	
Output Hold from Address Change	t <sub>on</sub>	10	-	15	-	15	-	ns	
Chip Selection to Output in Low Z	t, 7	10	-	10	-	10	-	ns	3
Output Enable to Output in Low Z	toz	5	-	5	-	5	-	ns	3
Chip Deselection to Output in High 2		0	30	0	35	0	45	ns	3
Output Disable to Output in High Z		0	30	0	35	0	45	ns	3

# Read Cycle Timing Waveform (1,2)



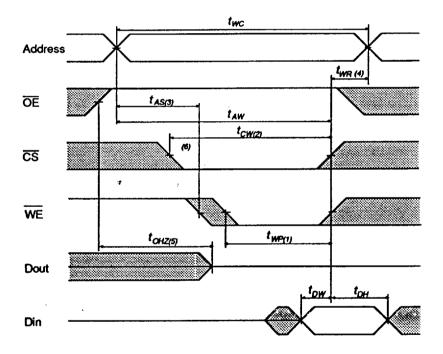
Notes (1) WE is High for Read Cycle.

- (2) Address valid prior to or coincident with CS transition Low.
- (3)  $t_{NZ}$  and  $t_{ONZ}$  are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels. These parameters are not tested but guaranteed by design.

3	ſ	ı		111	v	`-			
		PΙ	HAA	279	AΩ	~	06/1	0/4	^

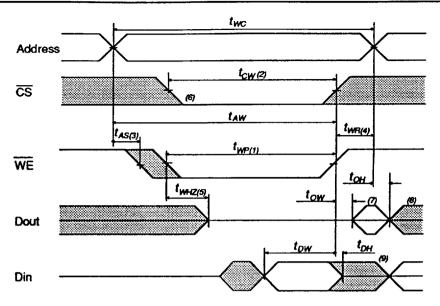
Write Cycle									
		8	35	1	0	1	2		
Parameter	Symbol	min	max	min	max	min	max	Units	Notes
Write Cycle Time	t <sub>wc</sub>	85	-	100	-	120	-	ns	
Chip Selection to End of Write	t <sub>cw</sub>	75	-	90	-	100	-	ns	
Address Valid to End of Write	t	<b>75</b>	-	90	-	100	-	ns	
Address Setup Time	tas	0	-	0	-	0	-	ns	
Write Pulse Width	twe	65	-	75	-	90	-	ns	
Write Recovery Time	t <sub>wR</sub>	5	-	5	-	10	-	ns	
Write to Output in High Z	t <sub>witz</sub>	0	30	0	35	0	40	ns	9
Data to Write Time Overlap	t <sub>pw</sub>	35	-	40	-	50	-	ns	
Data Hold from Write Time	t <sub>pH</sub>	0	-	0	-	0	-	ns	
Output Active from End of Write	tow	10	-	10	-	10	-	ns	

# Write Cycle No.1 Timing Waveform



**ISSUE 1.0: JANUARY 1993** 

# Write Cycle No.2 Timing Waveform

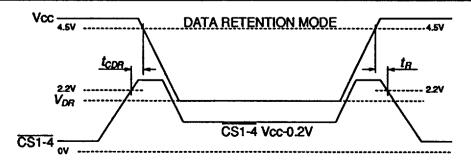


#### **AC Characteristics Notes**

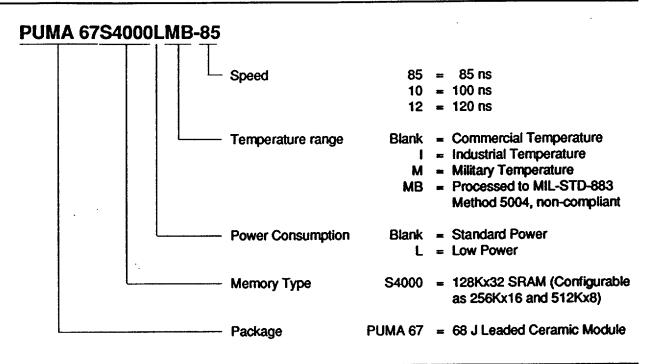
- (1) A write occurs during the overlap (twe) of a low  $\overline{\text{CS}}$  and a low  $\overline{\text{WE}}$ .
- (2) t is measured from the earlier of CS or WE going high to the end of write cycle.
- (3) During this period, I/O pins are in the output state. Input signals out of phase must not be applied.
- (4) If the CS low transition occurs simultaneously with the WE low transition or after the WE low transition, outputs remain in a high impedance state.
- (5) OE is continuously low. (OE=V\_)
- (6) Dout is in the same phase as written data of this write cycle.
- (7) Dout is the read data of next address.
- (8) If CS is low during this period, I/O pins are in the output state. Input signals out of phase must not be applied to I/O pins.
- (9) t<sub>wrz</sub> is defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels. This parameter is not tested but guaranteed by design.

Parameter	Symbol	Test Condition	min	typ(2)	max	Unit
V <sub>∞</sub> for Data Retention	VDB	<u>CS1-4</u> ≥V <sub>∞</sub> -0.2V	2.0	-		٧
Data Retention Current	ICCDR	V <sub>cc</sub> =3.0V, CS1-4≥2.8V, 0.2V≥V <sub>n</sub> ≥2.8V	-	4	1200	μΑ
CS high to Data Retention Time		See Retention Waveform	0	-	-	ns
Operation Recovery Time	t <sub>n</sub>	See Retention Waveform	5	-	-	ms

# Low V<sub>cc</sub> Data Retention Timing Waveform



# **Ordering Information**



The policy of the company is one of continuous development and while the information presented in this data sheet is believed to be accurate, no liability is assumed for any data contained within. The company reserves the right to make changes without notice at any time.

Semiconductor